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Microstructure evolution and deformation mechanisms during high rate and cryogenic sliding of copper

Xiang Chen, Reinhard Schneider, Peter Gumbsch, Christian Greiner

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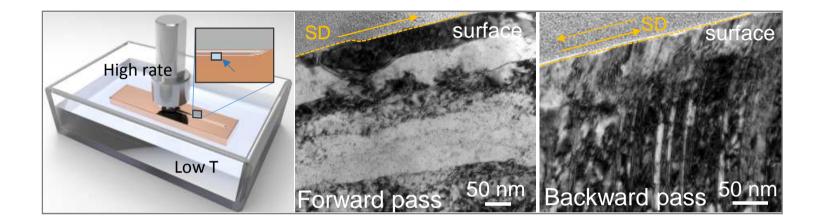
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